

Day : Friday
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PALM INTRANET

Inventor Name Search Result

Your Search was:

Last Name = NGUYEN

First Name = MY

Application#	Patent#	Status	Date Filed	Title	Inventor Name
<u>07915643</u>	5281790	150	07/21/1992	PROCESS OF IMMOBILIZING ASHES BY VITRIFICATION THEREOF IN A PLASMA REACTOR	NGUYEN HANDFIELD, MY D.
<u>09687768</u>	Not Issued	041	10/13/2000	THERMALLY CONDUCTIVE APPARATUSES AND METHODS OF MAKING AND USE	NGUYEN, MY
<u>09774466</u> ✓	6605238	150	01/30/2001	COMPLIANT AND CROSSLINKABLE THERMAL INTERFACE MATERIALS	NGUYEN, MY
<u>09851103</u> ✓	6706219	150	05/07/2001	INTERFACE MATERIALS AND METHODS OF PRODUCTION AND USE THEREOF	NGUYEN, MY
<u>10047617</u> ✓	6673434	150	01/14/2002	THERMAL INTERFACE MATERIALS	NGUYEN, MY
<u>10242139</u> ✓	6797382	150	09/09/2002	THERMAL INTERFACE MATERIALS	NGUYEN, MY
<u>10382784</u>	6756687	150	03/05/2003	INTERFACIAL STRENGTHENING FOR ELECTROLESS NICKEL IMMERSION GOLD SUBSTRATES	NGUYEN, MY
<u>10775370</u>	Not Issued	041	02/09/2004	INTERFACIAL STRENGTHENING FOR ELECTROLESS NICKEL IMMERSION GOLD SUBSTRATES	NGUYEN, MY
<u>60294433</u>	Not Issued	159	05/30/2001	INTERFACE MATERIALS AND METHODS OF PRODUCTION AND USE THEREOF	NGUYEN, MY

<u>60396294</u>	Not Issued	159	07/15/2002	THERMAL INTERCONNECT AND INTERFACE SYSTEMS, METHODS OF PRODUCTION AND USES THEREOF	NGUYEN, MY
<u>08922714</u>	Not Issued	161	09/02/1997	PROCESSLESS, LASER IMAGEABLE LITHOGRAPHIC PRINTING PLATE	NGUYEN, MY T.
<u>60372566</u>	Not Issued	159	04/14/2002	METHOD AND APPARATUS FOR ELECTROPOLISHING AND/OR ELECTROPLATING	NGUYEN, MY HOANG
<u>09333570</u>	6482387	150	06/16/1999	PROCESSES FOR PREPARING MIXED METAL OXIDE POWDERS	NGUYEN, MY HOANG
<u>10465968</u> ✓	Not Issued	160	01/01/0001	INTERFACE MATERIALS AND METHODS OF PRODUCTION AND USE THEREOF	NGUYEN, MY N
<u>10446891</u> ✓	6811725	150	05/27/2003	COMPLIANT AND CROSSLINKABLE THERMAL INTERFACE MATERIALS	NGUYEN, MY N.
<u>10715719</u> ✓	Not Issued	030	11/17/2003	THERMAL INTERFACE MATERIALS	NGUYEN, MY N.
<u>10775989</u> ✓	Not Issued	041	02/09/2004	INTERFACE MATERIALS AND METHODS OF PRODUCTION AND USE THEREOF	NGUYEN, MY N.
<u>07248120</u>	4986849	150	09/23/1988	SILVER-GLASS PASTES	NGUYEN, MY N.
<u>07482489</u>	5075262	150	02/21/1990	SILVER-GLASS PASTES	NGUYEN, MY N.
<u>07483050</u>	Not Issued	161	02/21/1990	SILVER-FILLED DIE ATTACH COMPOSITIONS AND USE OF SAME	NGUYEN, MY N.
<u>07604050</u>	5164119	150	10/29/1990	SILVER-GLASS PASTES	NGUYEN, MY N.
<u>07604236</u>	Not Issued	161	10/29/1990	IMPROVEMENTS IN SILVER-GLASS PASTES	NGUYEN, MY N.
<u>07654354</u>	Not Issued	164	02/08/1991	RAPID-CURING ADHESIVE FORMULATION FOR SEMICONDUCTOR DEVICES	NGUYEN, MY N.
<u>07760454</u>	5183784	150	09/17/1991	SILVER-GLASS PASTES	NGUYEN, MY N.
<u>07804116</u>	5155066	150	12/06/1991	RAPID-CURING ADHESIVE FORMULATION FOR SEMICONDUCTOR DEVICES	NGUYEN, MY N.

<u>07843735</u>	<u>5195299</u>	150	02/28/1992	METHOD OF REDUCING MOISTURE CONTENT OF HERMETIC PACKAGES CONTAINING SEMICONDUCTOR DEVICES	NGUYEN, MY N.
<u>07843738</u>	Not Issued	166	02/28/1992	LOW TEMPERATURE FLEXIBLE DIE ATTACH ADHESIVE AND ARTICLES USING SAME	NGUYEN, MY N.
<u>07843739</u>	Not Issued	166	02/28/1992	RAPIDLY CURING ADHESIVE AND METHOD	NGUYEN, MY N.
<u>07890618</u>	<u>5250600</u>	150	05/28/1992	LOW TEMPERATURE FLEXIBLE DIE ATTACH ADHESIVE AND ARTICLES USING SAME	NGUYEN, MY N.
<u>07945521</u>	Not Issued	166	09/16/1992	FAST-CURING ADHESIVE OF ADJUSTABLE VISCOSITY	NGUYEN, MY N.
<u>08032679</u>	Not Issued	166	03/17/1993	MATERIALS WITH LOW MOISTURE OUTGASSING PROPERTIES AND METHOD OF REDUCING MOISTURE CONTENT OF HERMETIC PACKAGES CONTAINING SEMICONDUCTOR DEVICES	NGUYEN, MY N.
<u>08068408</u>	<u>5399907</u>	150	05/27/1993	LOW TEMPERATURE FLEXIBLE DIE ATTACH ADHESIVE AND ARTICLES USING SAME	NGUYEN, MY N.
<u>08068794</u>	Not Issued	166	05/27/1993	LOW TEMPERATURE FLEXIBLE DIE ATTACH ADHESIVE AND ARTICLES USING SAME	NGUYEN, MY N.
<u>08134259</u>	Not Issued	166	10/08/1993	ADHESIVE SUITABLE FOR ATTACHING SEMICONDUCTOR DEVICES TO SUBSTRATES	NGUYEN, MY N.
<u>08162389</u>	<u>5386000</u>	150	12/03/1993	LOW TEMPERATURE FLEXIBLE DIE ATTACH ADHESIVE AND ARTICLES USING SAME	NGUYEN, MY N.
<u>08162390</u>	<u>5371178</u>	150	12/03/1993	RAPIDLY CURING ADHESIVE AND METHOD	NGUYEN, MY N.
<u>08186255</u>	Not Issued	166	01/24/1994	FAST-CURING ADHESIVE OF ADJUSTABLE VISCOSITY	NGUYEN, MY N.
<u>08187797</u>	Not Issued	166	01/25/1994	MATERIALS WITH LOW MOISTURE OUTGASSING	NGUYEN, MY N.

				PROPERTIES AND METHOD OF REDUCING MOISTURE CONTENT OF HERMETIC PACKAGES CONTAINING SEMICONDUCTOR DEVICES	
<u>08392602</u>	<u>5489637</u>	150	02/22/1995	LOW TEMPERATURE FLEXIBLE DIE ATTACH ADHESIVE AND ARTICLES USING SAME	NGUYEN, MY N.
<u>08430427</u>	Not Issued	166	04/28/1995	DIE ATTACH ADHESIVE WITH REDUCED RESIN BLEED	NGUYEN, MY N.
<u>08431685</u>	<u>5524422</u>	150	05/02/1995	MATERIALS WITH LOW MOISTURE OUTGASSING PROPERTIES AND METHOD OF REDUCING MOISTURE CONTENT OF HERMETIC PACKAGES CONTAINING SEMICONDUCTOR DEVICES	NGUYEN, MY N.
<u>08444530</u>	Not Issued	166	05/19/1995	ADHESIVE SUITABLE FOR ATTACHING SEMICONDUCTOR DEVICES TO SUBSTRATES	NGUYEN, MY N.
<u>08482804</u>	Not Issued	166	06/07/1995	FAST-CURING ADHESIVE	NGUYEN, MY N.
<u>08541129</u>	Not Issued	161	10/11/1995	FAST-CURING ADHESIVE OF ADJUSTABLE VISCOSITY	NGUYEN, MY N.
<u>08543321</u>	<u>5612403</u>	150	10/16/1995	LOW TEMPERATURE FLEXIBLE DIE ATTACH ADHESIVE AND ARTICLES USING SAME	NGUYEN, MY N.
<u>08587542</u>	Not Issued	161	01/17/1996	MATERIALS WITH LOW MOISTURE OUTGASSING PROPERTIES AND METHOD OF REDUCING MOISTURE CONTENT OF HERMETIC PACKAGES CONTAINING SEMICONDUCTOR DEVICES	NGUYEN, MY N.
<u>08627231</u>	Not Issued	161	03/19/1996	MATERIALS WITH LOW MOISTURE OUTGASSING PROPERTIES AND METHOD OF REDUCING MOISTURE CONTENT OF HERMETIC PACKAGES CONTAINING SEMICONDUCTOR DEVICES	NGUYEN, MY N.
<u>08629826</u>	Not Issued	161	04/10/1996	ORGANOSILICON COMPOSITIONS WITH	NGUYEN, MY N.

				RESISTANCE TO MOISTURE AND CONTROLLED MODULUS OF ELASTICITY	
<u>08680705</u>	<u>5708129</u>	150	07/17/1996	DIE ATTACH ADHESIVE WITH REDUCED RESIN BLEED	NGUYEN, MY N.
<u>08732914</u>	Not Issued	161	10/17/1996	ADHESIVE SUITABLE FOR ATTACHING SEMICONDUCTOR DEVICES TO SUBSTRATES	NGUYEN, MY N.

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